SSOP24 NB
CASE 565AL–01
ISSUE O

DATE 06 JUL 2010

NOTES:
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
   MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
   DIMENSION E1 DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION.
   INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 PER SIDE.
   D AND E1 ARE DETERMINED AT DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.

DIMENSIONS: MILLIMETERS

PITCH

RECOMMENDED SOLDERING FOOTPRINT

END VIEW

SIDE VIEW

TOP VIEW

DETAIL A

SEATING PLANE

DIIME L1 0.25 BSC

M 0 - 5

X = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER: 98AON52092E
DESCRIPTION: SSOP24 NB

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